



January 2009



# FDP8440

## N-Channel PowerTrench® MOSFET

### 40V, 277A, 2.2mΩ

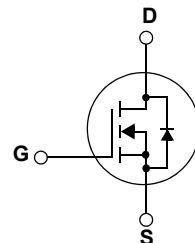
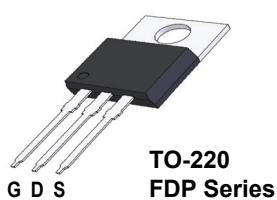
#### Features

- $R_{DS(on)} = 1.64\text{m}\Omega$  (Typ.)@  $V_{GS} = 10\text{V}$ ,  $I_D = 80\text{A}$
- $Q_{g(\text{tot})} = 345\text{nC}$  (Typ.)@  $V_{GS} = 10\text{V}$
- Low Miller Charge
- Low  $Q_{RR}$  Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- RoHS Compliant



#### Application

- Automotive Engine Control
- Powertrain Management
- Motors, Solenoids
- Electronic Steering
- Integrated Starter/ Alternator
- Distributed Power Architectures and VRMs
- Primary Switch for 12V Systems



#### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter		Ratings	Units
$V_{DSS}$	Drain to Source Voltage		40	V
$V_{GSS}$	Gate to Source Voltage		$\pm 20$	V
$I_D$	Drain Current	- Continuous ( $T_C = 25^\circ\text{C}$ , Silicon Limited) - Continuous ( $T_C = 100^\circ\text{C}$ , Silicon Limited) - Continuous ( $T_C = 25^\circ\text{C}$ , Package Limited)	277* 196* 100	A
$I_{DM}$	Drain Current	- Pulsed	(Note 1)	A
$E_{AS}$	Single Pulsed Avalanche Energy		(Note 2)	mJ
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ ) - Derate above $25^\circ\text{C}$	306 2.04	W $W/\text{^\circ C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +175	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	$^\circ\text{C}$

\*Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 100A.

#### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.49	$^\circ\text{C/W}$
$R_{\theta CS}$	Thermal Resistance, Case to Sink (Typ.)	0.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	$^\circ\text{C/W}$

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP8440	FDP8440	TO-220	N/A	N/A	50units

## Electrical Characteristics

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain to Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 32\text{V}$ $V_{\text{GS}} = 0\text{V}$	--	--	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Body Leakage Current	$V_{\text{GS}} = \pm 20\text{V}$	--	--	250	$\mu\text{A}$
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	Gate to Source Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	--	3	V
$R_{\text{DS}(\text{on})}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = 4.5\text{V}, I_D = 80\text{A}$	--	1.88	2.4	$\text{m}\Omega$
		$V_{\text{GS}} = 10\text{V}, I_D = 80\text{A}$	--	1.64	2.2	
		$V_{\text{GS}} = 10\text{V}, I_D = 80\text{A}, T_C = 175^\circ\text{C}$	--	3.00	4.4	
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0\text{MHz}$	--	18600	24740	pF
$C_{\text{oss}}$	Output Capacitance		--	1840	2450	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	1400	2100	pF
$R_G$	Gate Resistance	$V_{\text{GS}} = 0.5\text{V}, f = 1\text{MHz}$	--	1.1	--	$\Omega$
$Q_{\text{g}(\text{tot})}$	Total Gate Charge at 10V	$V_{\text{GS}} = 0\text{V}$ to $10\text{V}$	--	345	450	nC
$Q_{\text{g}(2)}$	Threshold Gate Charge	$V_{\text{GS}} = 0\text{V}$ to $2\text{V}$	$V_{\text{DD}} = 20\text{V}$ $I_D = 80\text{A}$ $I_g = 1.0\text{mA}$	32.5	--	nC
$Q_{\text{gs}}$	Gate to Source Gate Charge	49		--	nC	
$Q_{\text{gs}2}$	Gate Charge Threshold to Plateau	16.5		--	nC	
$Q_{\text{gd}}$	Gate to Drain "Miller" Charge	74		--	nC	
<b>Switching Characteristics</b> ( $V_{\text{GS}} = 10\text{V}$ )						
$t_{\text{ON}}$	Turn-On Time	$V_{\text{DD}} = 20\text{V}, I_D = 80\text{A}$ $V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 7\Omega$	--	175	360	ns
$t_{\text{d}(\text{on})}$	Turn-On Delay Time		--	43	95	ns
$t_r$	Rise Time		--	130	275	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		--	435	875	ns
$t_f$	Fall Time		--	290	590	ns
$t_{\text{OFF}}$	Turn-Off Time		--	730	1470	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$V_{\text{SD}}$	Source to Drain Diode Voltage	$I_{\text{SD}} = 80\text{A}$	--	--	1.25	V
		$I_{\text{SD}} = 40\text{A}$	--	--	1.0	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_{\text{SD}} = 75\text{A}, dI_{\text{SD}}/dt = 100\text{A}/\mu\text{s}$	--	59	--	ns
$Q_{\text{RR}}$	Reverse Recovery Charge	$I_{\text{SD}} = 75\text{A}, dI_{\text{SD}}/dt = 100\text{A}/\mu\text{s}$	--	77	--	nC

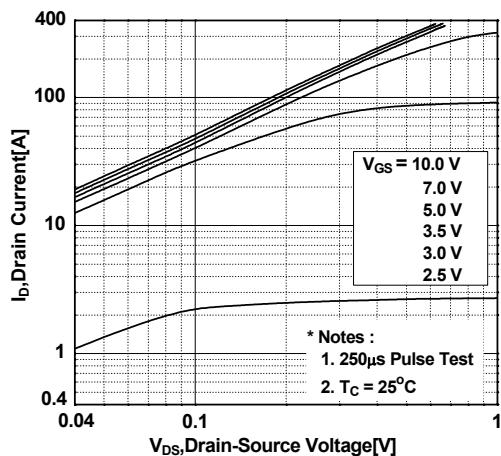
### NOTES:

1: Pulse width limited by maximum junction temperature.

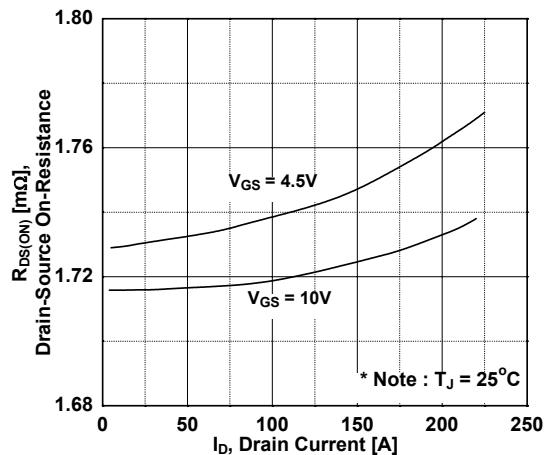
2: Starting  $T_J = 25^\circ\text{C}$ ,  $L = 1\text{mH}$ ,  $I_{\text{AS}} = 58\text{A}$ ,  $V_{\text{DD}} = 36\text{V}$ ,  $V_{\text{GS}} = 10\text{V}$ .

## Typical Performance Characteristics

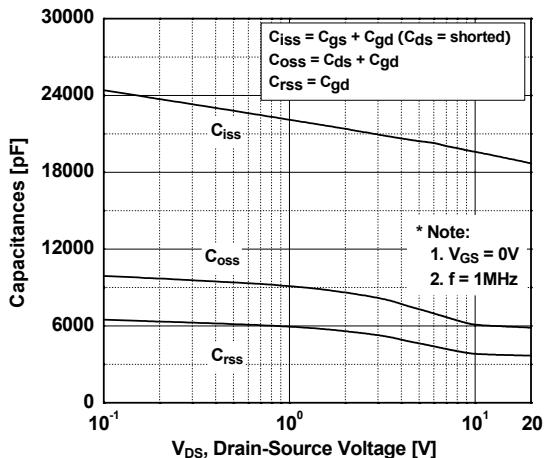
**Figure 1. On-Region Characteristics**



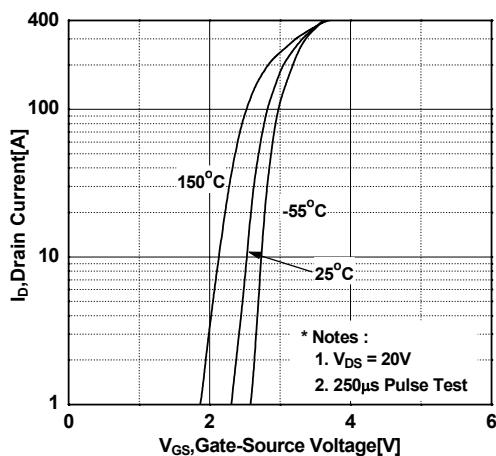
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



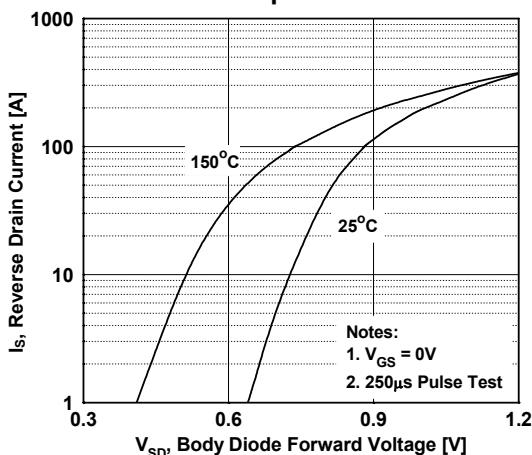
**Figure 5. Capacitance Characteristics**



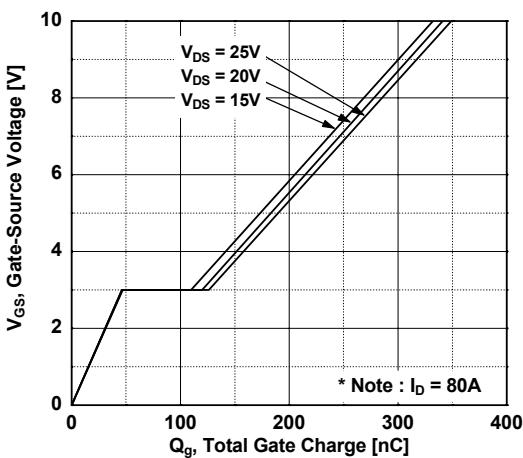
**Figure 2. Transfer Characteristics**



**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**

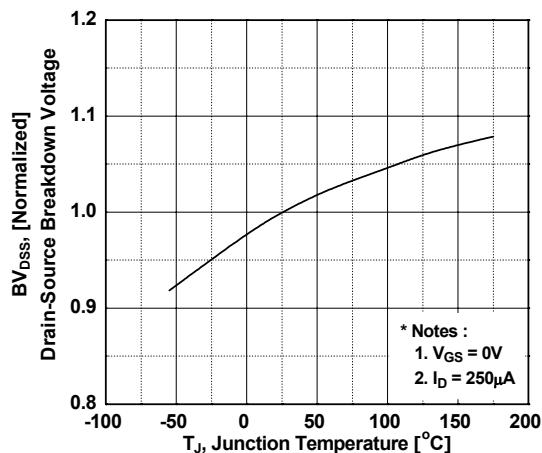


**Figure 6. Gate Charge Characteristics**

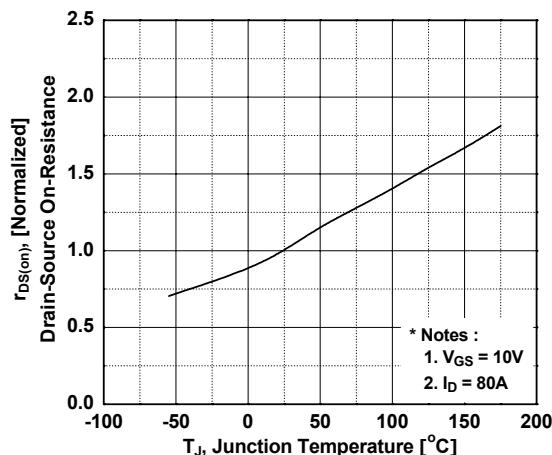


## Typical Performance Characteristics (Continued)

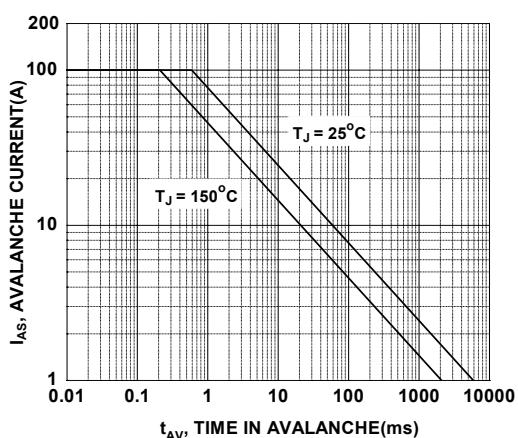
**Figure 7. Breakdown Voltage Variation vs. Temperature**



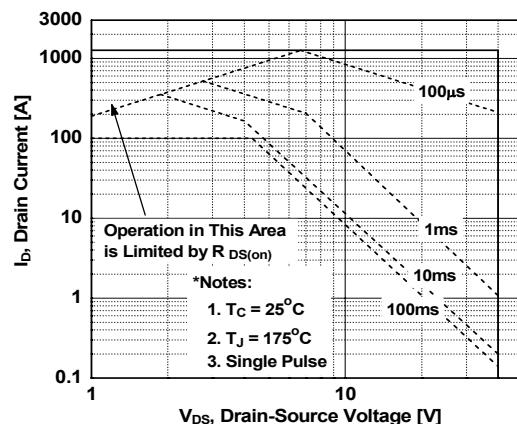
**Figure 8. On-Resistance Variation vs. Temperature**



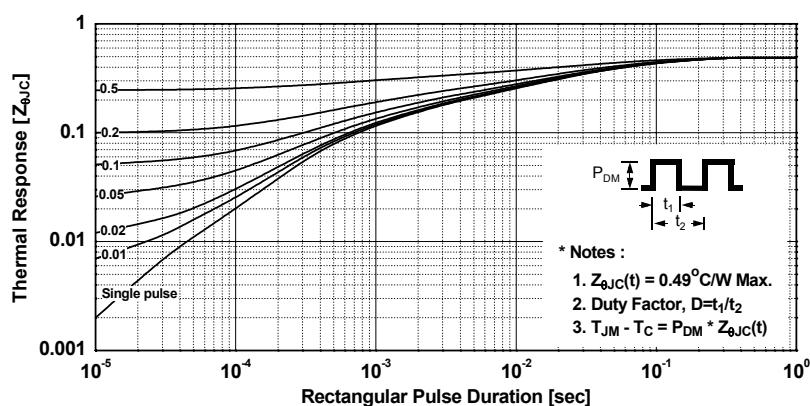
**Figure 9. Unclamped Inductive Switching Capability**



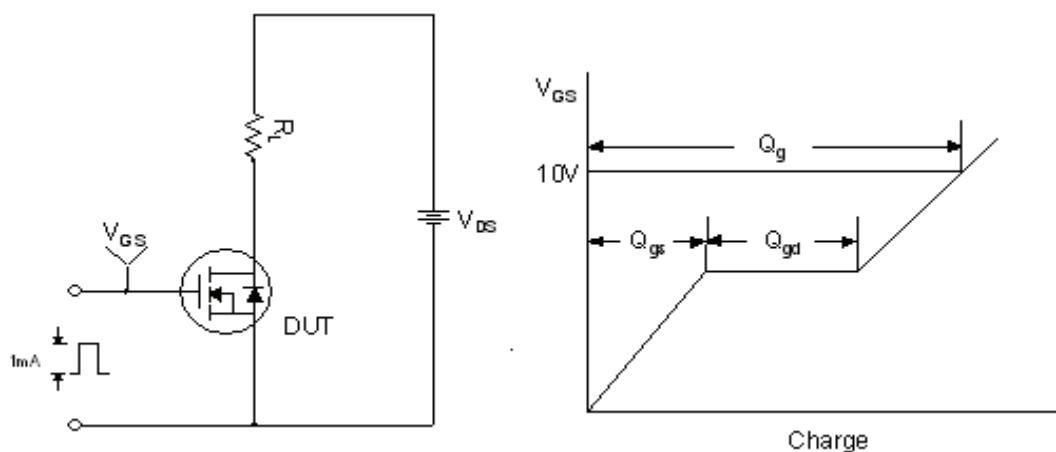
**Figure 10. Safe Operating Area**



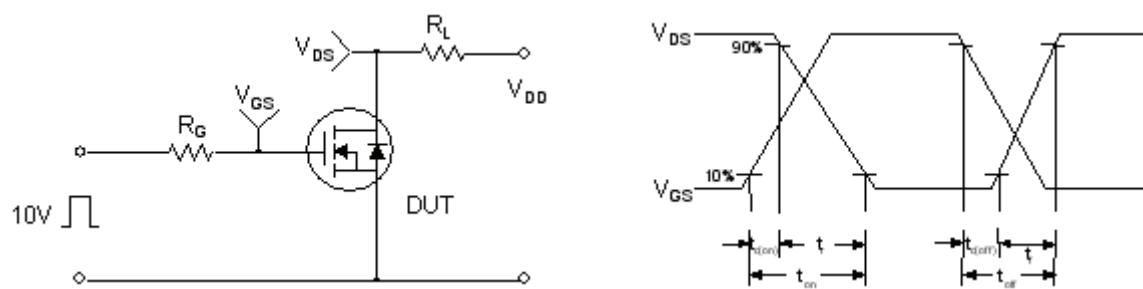
**Figure 11. Transient Thermal Response Curve**



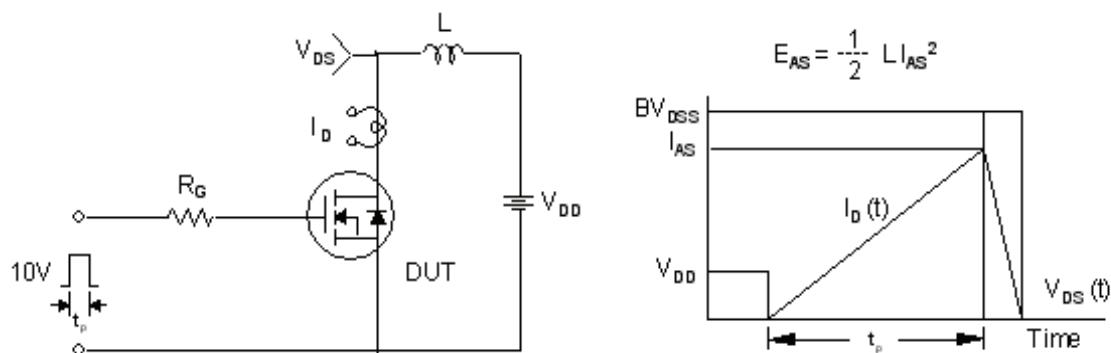
**Gate Charge Test Circuit & Waveform**



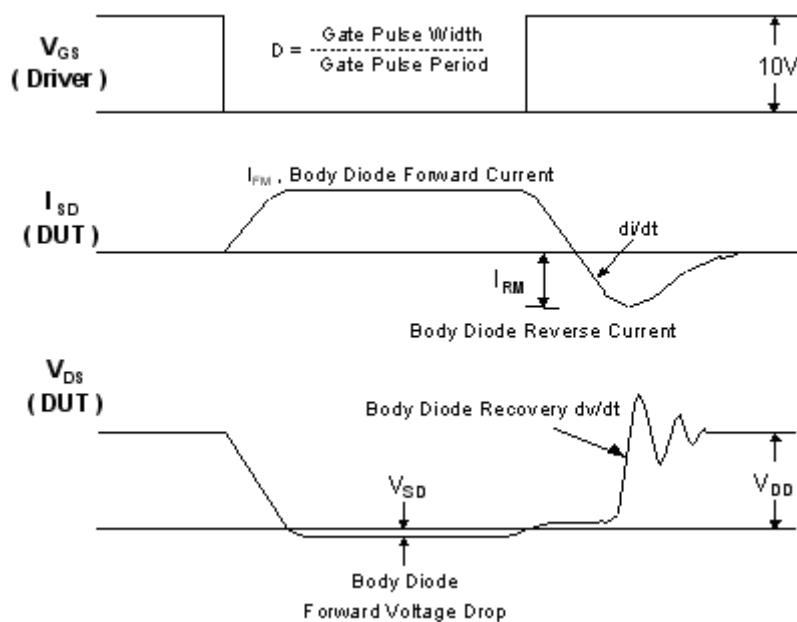
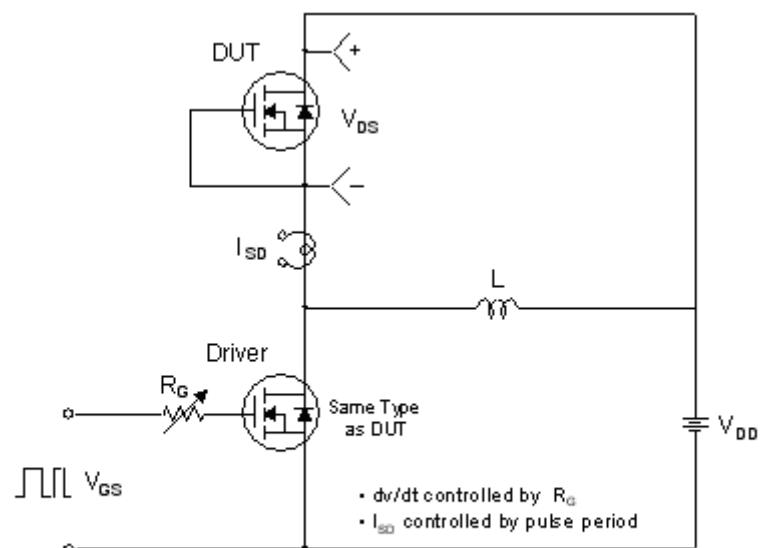
**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**

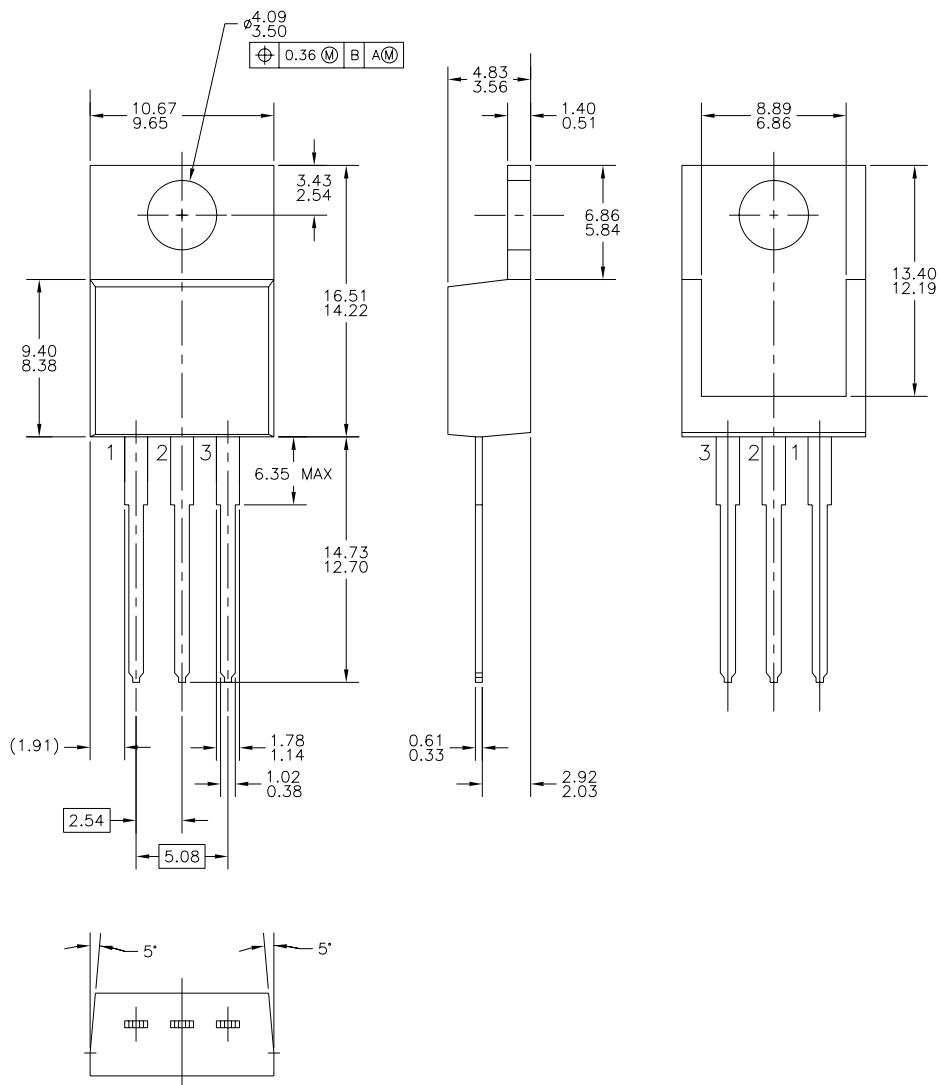


Peak Diode Recovery dv/dt Test Circuit & Waveforms



## Mechanical Dimensions

TO-220





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